



Material Content Data Sheet



Sales Product Name		TLE7276-2E		Issued		27. September 2017		
MA#		MA000970652						
Package		PG-SSOP-14-2		Weight*		83.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.717	2.07	2.07	20651	20651
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.689	0.83		8289	
wire	non noble metal	copper	7440-50-8	27.978	33.66	34.54	336570	345377
	noble metal	gold	7440-57-5	0.109	0.13	0.13	1307	1307
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
plastics	plastics	epoxy resin	-	4.573	5.50		55016	
		silicondioxide	60676-86-0	45.036	54.18	59.80	541785	597997
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11743	11743
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9234	9234
glue	plastics	epoxy resin	-	0.285	0.34		3423	
		noble metal	silver	7440-22-4	0.854	1.03	1.37	10268
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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